SUBSTRATE PROCESSING APPARATUS, NOZZLE ADAPTER, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, SUBSTRATE PROCESSING METHOD AND PROGRAM

[ABSTRACT]

There is provided a technique capable of reducing a tilt of a nozzle. According to one aspect of the technique, there is provided a substrate processing apparatus including: a process vessel constituted by a reaction tube and a manifold supporting the reaction tube from thereunder and in which a substrate is processed; a nozzle through which a process gas is supplied to the substrate; a metal adapter configured to hold the nozzle vertically in the process vessel; a support base arranged below the metal adapter and fixed to the manifold; and a fixing bolt engaging with the support base and screwed into the metal adapter.

Figure 1